

ALPHA[®] OM-362

Ultra-Low Voiding, High-Reliability Solder Paste

ALPHA OM-362 is a lead-free, zero-halogen, no-clean solder paste available in T4 powder. It is designed to provide ultra-low voiding performance on all component types including bottom terminated components.

ALPHA OM-362 achieves IPC Class III voiding on BGA components averaging less than 10% voiding on Bottom Terminated Components (BTC). This paste is designed for ultra-low voiding performance with high reliability alloys such as Innolot as well as traditional SAC alloys.



KEY ATTRIBUTES

- **Ultra-Low Voiding Performance:** Enables increased process stability, and enhances thermal and electrical performance of the most demanding component applications.
- **Excellent Electromigration Characteristics:** Passes J-STD-004C IPC-TM-650 at 200 μ m to ensure electrical reliability & functionality of fine-pitched components.
- **Wide Reflow Profile Window:** Enables high quality solderability of complicated, high density PCB assemblies using straight ramp and soak profiles, as high as 150° to 200°C soak.
- **Good Coalescence and Wetting Performance:** Coalesces down to 180 μ m exhibiting good wetting characteristics and solder joint reliability.
- **Excellent Solder Joint and Flux Residue Cosmetics:** Easily penetrable and clear flux residue enables good probe contact during quality inspection.
- **Zero-Halogen, No Halogens Intentionally Added:** Ensures RoHS compliance for a safe and environmentally friendly assembly process.



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